μPD720211

ASSP (Two-port USB3.0 Hub Controller)

R19DS0080EJ0510
Rev.5.10
Sep 25, 2023

1. OVERVIEW

The μPD720211 is a USB 3.0 hub controller that complies with the Universal Serial Bus (USB) Specification Revision 3.0 and operates at up to 5 Gbps. The device incorporates Renesas' market proven design expertise in USB 3.0 interface technologies and market proven USB 2.0 hub core. The device is fully compatible with all prior versions of USB spec and 100% compatible with Renesas' industry standard USB 3.0 host controller. It comes in a small 56-pin QFN package and integrates several commonly required external components, making it ideally suited for applications with limited PCB space. In addition, the μPD720211 incorporates Renesas' low-power technologies and supports all mainstream battery charging specifications.

1.1 Features

- Compliant with Universal Serial Bus 3.0 Specification Revision 1.0, which is released by USB Implementers Forum, Inc
  - Supports the following speed data rates: Low-speed (1.5 Mbps) / Full-speed (12 Mbps) / High-speed (480 Mbps) / Superspeed (5 Gbps)
  - Supports USB 3.0 link power management (U0/U1/U2/U3)
  - Supports USB 2.0 link power management (LPM: L0/L1/L2/L3)
- Supports two downstream ports
- Supports all VBUS control options
  - Individual or global over-current detection
  - Individual or ganged power control
- Supports USB 3.0/2.0 Compound (non-removable) devices by I/O pin configuration
- Supports clock output (24/12 MHz) for Compound (non-removal) device on downstream ports
- Supports Energy Star and EuP specifications for low-power PC peripheral system
- Single 3.3 V Power Supply
  - On chip Switching Regulator for 1.05 V from 3.3 V input
- System clock: 24 MHz Crystal or Oscillator
- Supports USB Battery Charging Specification Revision 1.2 and other portable devices
  - DCP mode of BC 1.2
  - CDP mode of BC 1.2
  - ACA-Dock function of BC 1.2
  - China Mobile Phone Chargers
  - EU Mobile Phone Chargers
  - Apple iOS products
  - Other major portable devices
- Supports SPI ROM for optional firmware and parameter data
  - UUID supported with ROM Writing Tools
- Small Footprint
  - Small and low pin count package with simple pin assignment for PCB layout
  - Integration of many peripheral components
  - Direct routing of all USB signal traces to connector pins using one layer of the PCB
- Self/Bus-Powered modes can be set by pin strapping
- Integrated termination resistors for USB
- Provides SUSPEND status output

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1.2 Applications

Standalone Hub, Monitor-Hub, Docking Station, Integrated Hub, etc.

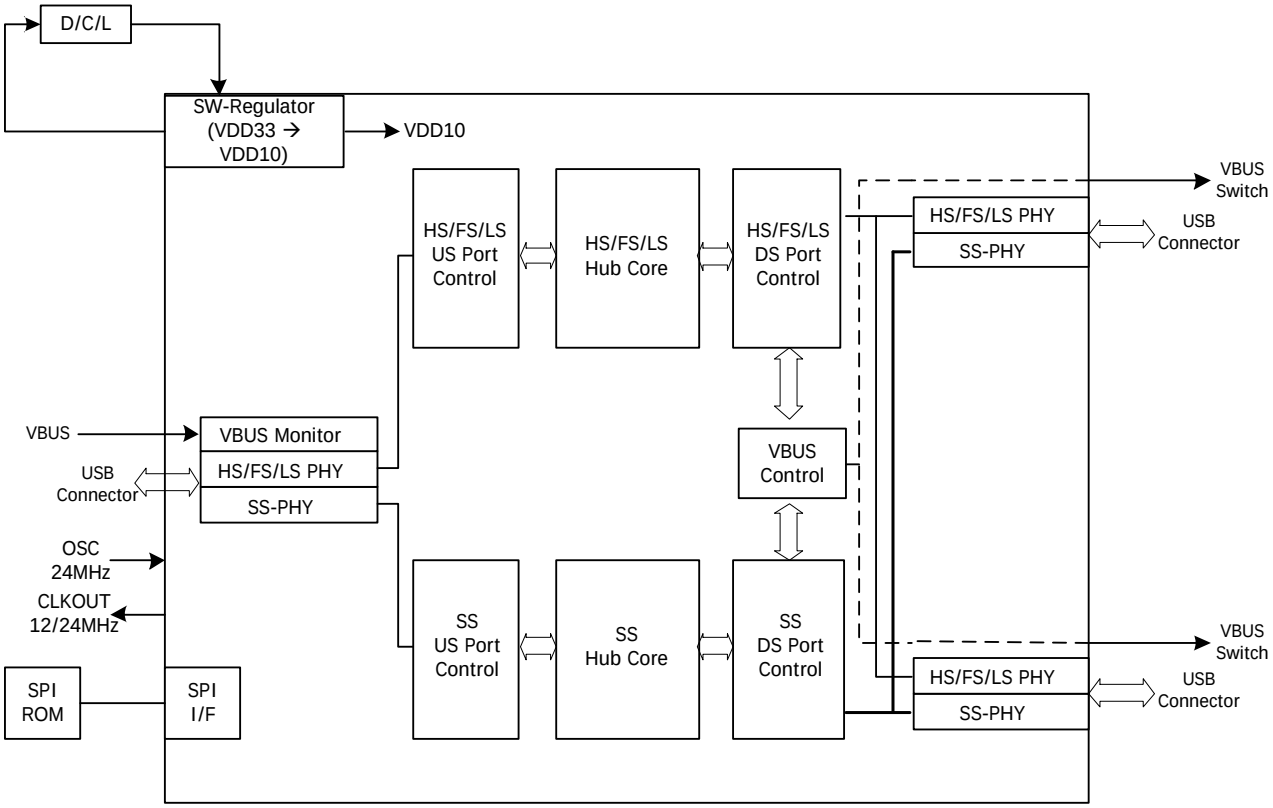
1.3 Ordering Information

Part Number	Package	Packing form	Operating Temperature	Remark
μPD720211K8-611-BAL-A	56-pin QFN (8 × 8)	Fraction (any vacancy in the tray and any free space in the carton)	0 to +70°C	Lead-free product
μPD720211K8-611-BAL-M1-A		Full Carton (tray and Carton is packed with every product)		
μPD720211K8-711-BAL-A		Fraction	−40 to +70°C	Lead-free product
μPD720211K8-711-BAL-M1-A		Full Carton		

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1.4 Block Diagram

Figure 1-1. μPD720211 Block Diagram



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Table 1-1. Terminology

Block Name	Description
SS PHY	SuperSpeed Tx/Rx
HS/FS/LS PHY	High-/Full-/Low-speed transceiver
VBUS Monitor	Monitors the VBUS voltage level of the upstream port.
SS US Port Control	Upstream port control logic for SuperSpeed
HS/FS/LS US Port Control	Upstream port control logic for High-/Full-/Low-speed
SS Hub Core	Central control logic for SS-Hub.
HS/FS/LS Hub Core	Central control logic for HS/FS/LS-Hub.
SS DS Port Control	Downstream port control logic for SuperSpeed
HS/FS/LS DS Port Control	Downstream port control logic for HS/FS/LS
VBUS Control	Controls all the external port power switches
SPI Interface	Connected to external serial ROM which can hold the optional firmware and hub settings
SW-Regulator	Switching regulator control logic to output 1.05 V power from 3.3 V input.
D/C/L	D: Schottky Barrier Diode, C: Capacitor 22 μF, L: Inductor 4.7 μH

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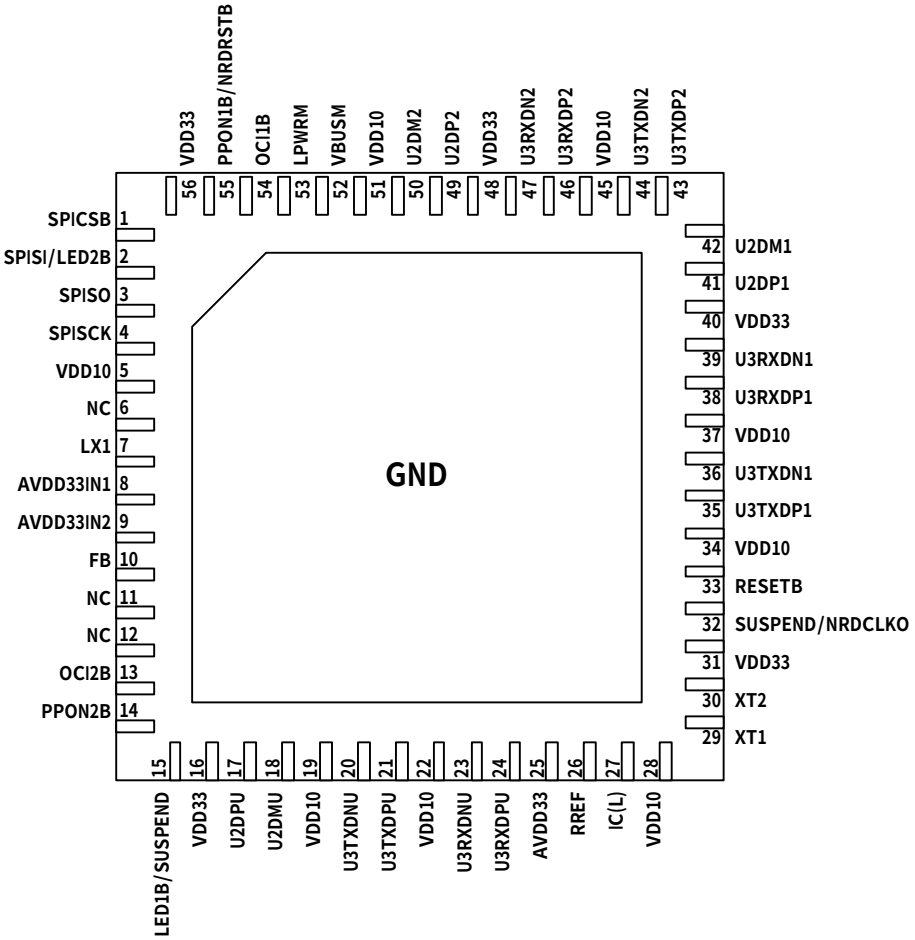
1.5 Pin Configuration

- **56-pin QFN (8 × 8)**

  μPD720211K8-611-BAL-A / μPD720211K8-611-BAL-M1-A

  μPD720211K8-711-BAL-A / μPD720211K8-711-BAL-M1-A

Figure 1-2. Pin Configuration of μPD720211 (Top View)



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2. PIN FUNCTION

This section describes each pin function.

Strapping information in the tables shows how the pin can be used to configure the functional settings of this controller when the pin is pulled up/down, as detected at the end of chip reset.

2.1 Power Supply

Pin Name	Pin No.	I/O Type	Function
VDD10	5, 19, 22, 28, 34, 37, 45, 51	Power	1.05 V power supply for Core Logic
VDD33	16, 31, 40, 48, 56	Power	3.3 V power supply for IO buffer
AVDD33	25	Power	3.3 V power supply for Analog circuit
AVDD33IN1	8	Power	SW Regulator 3.3 V Input
AVDD33IN2	9	Power	SW Regulator 3.3 V Input
LX1	7	-	SW Regulator 1.05 V Output
FB	10	-	SW Regulator Output Monitor

2.2 Analog Interface

Pin Name	Pin No.	I/O Type	Function
RREF	26	-	Reference Voltage Input for USB 2.0 RREF must be connected to a 1.6 kΩ resistor with a tolerance of +/- 1%. It is strongly recommended to use a single resistor of 1.6 kΩ, versus the combined resistance with multiple resistors to achieve the value and tolerance.

2.3 System Clock

Pin Name	Pin No.	I/O Type	Function
XT1	29	IN	External Oscillator Input Connect to 24 MHz crystal. Alternatively, this pin can accept a 3.3 V Oscillator input.
XT2	30	OUT	External Oscillator Output Connect to 24 MHz crystal. When using single-ended clock input to XT1, this pin should be left open.

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2.4 System Interface Pins

<table>
<tr><th>Pin Name</th><th>Pin No.</th><th>I/O Type</th><th>Active Level</th><th>Function</th></tr>
<tr><td>SUSPEND/NRDCLKO</td><td>32</td><td>OUT</td><td>High/NA</td><td>SUSPEND Output or CLKOUT depending on pin strap setting of SPICSB and OCI1B.
SUSPEND is Suspend state output.
1: in suspend state.
0: not in suspend state.
When ACA-Dock function is selected, this pin is used for ACA-Dock function.
This signal is the control of VBUS. (Low active, Open-drain output)
See User's Manual for additional details about ACA-Dock function.
[Note]
SUSPEND/NRDCLKO output level is Hi-Z till this pin function is configured as SUSPEND output or clock output for non-removable device.
<table>
<tr><th>SPICSB</th><th>OCI1B</th><th>LED1B/ SUSPEND</th><th>Pin Function</th></tr>
<tr><td rowspan="2">Low</td><td>Low</td><td>X</td><td>NRDCLKO</td></tr>
<tr><td>High</td><td>X</td><td>SUSPEND</td></tr>
<tr><td>Low</td><td>X</td><td>Low</td><td>ACA-Docking function for VBUS control</td></tr>
<tr><td>High</td><td>X</td><td>X</td><td>Depends on Serial ROM setting (Set NRDCLKO or SUSPEND.Cannot set ACA-Docking function)</td></tr>
</table>
</td></tr>
<tr><td>VBUSM</td><td>52</td><td>IN</td><td>High</td><td>Upstream Port VBUS Monitor
Divide VBUS to 3.3 V and connect to VBUSM</td></tr>
<tr><td>LPWRM</td><td>53</td><td>IN</td><td>N/A</td><td>Local power monitor input
0: Local power is lost.
1: Local power is supplied.
This value is set to Self Powered field of Device Status dynamically.</td></tr>
<tr><td>LED1B/SUSPEND</td><td>15</td><td>I/O</td><td>Low</td><td>When the external ROM is used (SPICSB is high) and SUSPEND function is enabled in the ROM Writing Tool, LED1B/SUSPEND is used as SUSPEND function. If the SUSPEND function is not enabled, this pin is not functional (Hi-Z).
When ACA-Dock function is selected, this pin is used for ACA-Dock function.
This signal is the control of RID. (High active, Push-pull output)
See User's Manual for additional details about ACA-Dock function.

[Function]
Suspend state is shown by the following pin level.
1: in suspend state.
0: not in suspend state.
<table>
<tr><th>LED1B/ SUSPEND</th><th>SPICSB</th><th>SPISI/ LED2B</th><th>Pin Function</th></tr>
<tr><td>High</td><td>Low</td><td>Low</td><td>Reserved</td></tr>
<tr><td>Low</td><td>Low</td><td>X</td><td>ACA-Docking function for RID control</td></tr>
<tr><td>High</td><td>High</td><td>X</td><td>SUSPEND or Hi-Z</td></tr>
</table>
</td></tr>
<tr><td>RESETB</td><td>33</td><td>IN</td><td>Low</td><td>Chip Reset Input.</td></tr>
</table>

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2.5 USB Port Control Pins

<table>
<tr><th>Pin Name</th><th>Pin No.</th><th>I/O Type</th><th>Active Level</th><th>Function</th></tr>
<tr><td>OCI1B</td><td>54</td><td>IN</td><td>Low</td><td>[Function]
Over Current Input.
0: Over-current condition is detected.
1: Non over-current condition is detected.
[Pin strapping option]
<table><tr><td>OCI1B</td><td>Pin Function</td></tr><tr><td>High</td><td>Removable device setting and Over current input.</td></tr><tr><td>Low</td><td>Non-Removable setting.</td></tr></table>This pin is used to select non-removable setting.</td></tr>
<tr><td>OCI2B</td><td>13</td><td>IN</td><td>Low</td><td>[Function]
Over Current Input
0: Over-current condition is detected.
1: Non over-current condition is detected.
[Pin strapping option]
<table><tr><td>OCI2B</td><td>Pin Function</td></tr><tr><td>High</td><td>Removable device setting and Over Current Input.</td></tr><tr><td>Low</td><td>Non-Removable setting.</td></tr></table>This pin is used to select non-removable setting.</td></tr>
<tr><td>PPON1B/NRDRSTB</td><td>55</td><td>I/O</td><td>Low</td><td>[Function]
Port Power Control or NRDRSTB (Non-Removable Device Reset) depending on pin strap setting of this pin.
<table><tr><td>PPON1B/NRDRSTB</td><td>Pin Function</td></tr><tr><td>High</td><td>PPON1B</td></tr><tr><td>Low</td><td>NRDRSTB</td></tr></table>PPON1B is a Port Power Control signal
0: Power supply for VBUS is on.
1: Power supply for VBUS is off.
NRDRSTB is a reset signal for Non-Removable device.
[Pin strapping option]
This pin is used for pin strapping options.</td></tr>
<tr><td>PPON2B</td><td>14</td><td>I/O</td><td>Low</td><td>[Function]
PPON2B is a Port Power Control signal.
0: Power supply for VBUS is on.
1: Power supply for VBUS is off.
[Pin strapping option]
This pin is used for pin strapping option: Gang/Individual Power Control of all ports.
<table><tr><td>PPON2B</td><td>Gang/Individual Mode</td></tr><tr><td>High</td><td>Individual</td></tr><tr><td>Low</td><td>Gang</td></tr></table></td></tr>
</table>

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2.6 USB Data Pins

Pin Name	Pin No.	I/O Type	Function
U3TXDN1, U3TXDN2	36, 44	OUT	USB 3.0 Downstream Transmit data D- signal for SuperSpeed
U3TXDNU	20	OUT	USB 3.0 Upstream Transmit data D- signal for SuperSpeed
U3TXDP1, U3TXDP2	35, 43	OUT	USB 3.0 Downstream Transmit data D+ signal for SuperSpeed
U3TXDPU	21	OUT	USB 3.0 Upstream Transmit data D+ signal for SuperSpeed
U3RXDN1, U3RXDN2	39, 47	IN	USB 3.0 Downstream Receive data D- signal for SuperSpeed
U3RXDNU	23	IN	USB 3.0 Upstream Receive data D- signal for SuperSpeed
U3RXDP1, U3RXDP2	38, 46	IN	USB 3.0 Downstream Receive data D+ signal for SuperSpeed
U3RXDPU	24	IN	USB 3.0 Upstream Receive data D+ signal for SuperSpeed
U2DM1, U2DM2	42, 50	I/O	USB 2.0 Downstream D- signal for High-/Full-/Low-speed
U2DMU	18	I/O	USB 2.0 Upstream D- signal for High-/Full-/Low-speed
U2DP1, U2DP2	41, 49	I/O	USB 2.0 Downstream D+ signal for High-/Full-/Low-speed
U2DPU	17	I/O	USB 2.0 Upstream D+ signal for High-/Full-/Low-speed

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2.7 SPI Interface

<table>
<tr><th>Pin Name</th><th>Pin No.</th><th>I/O Type</th><th>Active Level</th><th>Function</th></tr>
<tr><td>SPISCK</td><td>4</td><td>I/O</td><td>N/A</td><td>[Function]
External serial ROM Clock Output

[Pin strapping option]
This pin is used for pin strapping option to select U1/U2 function.
<table>
<tr><td>SPICSB</td><td>SPISCK</td><td>U1/U2 Function</td></tr>
<tr><td>High</td><td>X</td><td>Depends on Serial ROM Setting</td></tr>
<tr><td rowspan="2">Low</td><td>High</td><td>Enable U1/U2 function</td></tr>
<tr><td>Low</td><td>Disable U1/U2 function</td></tr>
</table></td></tr>
<tr><td>SPICSB</td><td>1</td><td>I/O</td><td>Low</td><td>[Function]
External serial ROM Chip Select.
<table>
<tr><td>SPICSB</td><td>Pin Function</td></tr>
<tr><td>High</td><td>Use External ROM</td></tr>
<tr><td>Low</td><td>Not use External ROM</td></tr>
</table>
[Pin strapping option]
This pin is used for pin strapping option to select whether external ROM is used.
And, this pin setting also have an impact for U1/U2 function, LED1B/SUSPEND, SUSPEND/NRDCLKO and SPISI/LED2B. Moreover, it is necessary to set Pin strapping as below depending on ROM address bit length.
<table>
<tr><td>SPISO</td><td>SPISI/LED2B</td><td>LED1B/SUSPEND</td><td>Function</td></tr>
<tr><td colspan="3">Others</td><td>16bit (1)</td></tr>
<tr><td>Low</td><td>High</td><td>High</td><td>24bit (2)</td></tr>
</table>
(1) Only EEPROM is supported.
(2) Only Flash ROM is supported
“Others”: this means SPISO and SPISI/LED2B should set to different pin setting with 24bit function.</td></tr>
<tr><td>SPISO</td><td>3</td><td>I/O</td><td>N/A</td><td>[Function]
External serial ROM Data Input (to be connected to Serial Data Output pin of the external ROM).

[Pin strapping option]
This pin is used for pin strapping option to select Battery Charging (BC) mode when not using Serial ROM.
<table>
<tr><td>SPISO</td><td>SPISI/LED2B</td><td>BC Mode</td></tr>
<tr><td>High</td><td>High</td><td>SDP</td></tr>
<tr><td>High</td><td>Low</td><td>CDP + FVO2 (port2) Note1</td></tr>
<tr><td>Low</td><td>High</td><td>CDP+ Auto(port2)Note1</td></tr>
<tr><td>Low</td><td>Low</td><td>CDP + Auto(all ports)Note2</td></tr>
</table></td></tr>
<tr><td>SPISI/LED2B</td><td>2</td><td>I/O</td><td>N/A</td><td>[Function]
External serial ROM Data Output (to be connected to Serial Data input pin of the external ROM) depending on pin strap setting of SPICSB.
<table>
<tr><td>SPICSB</td><td>LED1B/SUSPEND</td><td>SPISI/LED2B</td><td>Function</td></tr>
<tr><td>High</td><td>High</td><td>Low</td><td>SPISI</td></tr>
<tr><td>High</td><td>High</td><td>High</td><td>SPISI</td></tr>
<tr><td>Low</td><td>X</td><td>Low</td><td>Reserved</td></tr>
</table>
[Pin strapping option]
This pin is used for pin strapping options.</td></tr>
</table>

Notes 1. Only port2 supports battery charging.

2. All removable ports among available ones support battery charging.

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2.8 Test Pin

Pin Name	Pin No.	I/O Type	Active Level	Function
IC(L)	27	IN	High	IC(L) pin to be connected to GND
NC	6, 11, 12	N/A	N/A	NC pin to be open.

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3. ELECTRICAL SPECIFICATIONS

3.1 Buffer List

Pin Name	Buffer Type	Strap Pin
XT1	3.3 V oscillator interface	
XT2	3.3 V oscillator interface	
SUSPEND/NRDCLKO	SUSPEND : 3.3 V I_{OLH} = 4 mA output buffer	
	NRDCLKO : 3.3 V I_{OLH} = 4 mA output buffer	
	ACA Docking function : 3.3 V I_{OL} = 4 mA open drain buffer	
VBUSM	3.3 V input Schmitt buffer (5 V tolerant)	
LPWRM	3.3 V input Schmitt buffer (5 V tolerant)	
LED1B/SUSPEND	LED1B : 3.3 V I_{OL} = 12 mA open drain buffer (Note2)	Yes (Note1)
	SUSPEND : 3.3 V I_{OL} = 12 mA output buffer	
	ACA Docking function : 3.3 V I_{OL} = 12 mA output buffer	
RESETB	3.3 V input Schmitt buffer	
OCI1B	3.3 V input Schmitt buffer (5 V tolerant)	Yes (Note1)
OCI2B	3.3 V input Schmitt buffer	Yes (Note1)
PPON1B/NRDRSTB	PPON1B : 3.3 V I_{OL} = 4 mA open drain buffer	Yes (Note1)
	NRDRSTB : 3.3 V I_{OLH} = 4 mA output buffer	
PPON2B	3.3 V I_{OL} = 4 mA open drain buffer	Yes (Note1)
U3TXDP(2:1, U),U3TXDN(2:1, U) U3RXDP(2:1, U),U3RXDN(2:1, U)	USB SuperSpeed Serdes (Serializer-Deserializer)	
U2DP(2:1, U),U2DM(2:1, U)	USB Classic interface	
SPISCK	3.3 V I_{OL} = 12 mA output buffer	Yes (Note1)
SPICSB	3.3 V I_{OLH} = 4 mA output buffer	Yes (Note1)
SPISO	3.3 V input buffer	Yes (Note1)
SPISI/LED2B	SPISI : 3.3 V I_{OL} = 12 mA output buffer	Yes (Note1)
	LED2B : 3.3 V I_{OL} = 12 mA open drain buffer (Note2)	
IC(L)	3.3 V input buffer	

Notes 1. The pins used for pin strap setting are input buffer during asserting RESETB and for 3us after de-asserting RESETB.

2. LED function is not supported.

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3.2 Terminology

Table 3-1. Terms Used in Absolute Maximum Ratings

Parameter	Symbol	Meaning
Power supply voltage	V_{DD33}, V_{DD10}, AV_{DD33}, $AV_{DD33IN1}$, $AV_{DD33IN2}$	Indicates the voltage range within which damage or reduced reliability will not result when power is applied to a VDD pin.
Input voltage	V_I	Indicates voltage range within which damage or reduced reliability will not result when power is applied to an input pin.
Output voltage	V_O	Indicates voltage range within which damage or reduced reliability will not result when power is applied to an output pin.
Output current	I_O	Indicates absolute tolerance values for DC current to prevent damage or reduced reliability when current flows out of or into output pin.
Storage temperature	T_{stg}	Indicates the element temperature range within which damage or reduced reliability will not result while no voltage or current is applied to the device.

Table 3-2. Terms Used in Recommended Operating Range

Parameter	Symbol	Meaning
Power supply voltage	V_{DD33}, V_{DD10}, AV_{DD33}, $AV_{DD33IN1}$, $AV_{DD33IN2}$	Indicates the voltage range for normal logic operations occur when GND = 0 V.
High-level input voltage	V_{IH}	Indicates the voltage, which is applied to the input pins of the device, is the voltage indicates that the high level states for normal operation of the input buffer. * If a voltage that is equal to or greater than the “Min.” value is applied, the input voltage is guaranteed as high level voltage.
Low-level input voltage	V_{IL}	Indicates the voltage, which is applied to the input pins of the device, is the voltage indicates that the low level states for normal operation of the input buffer. * If a voltage that is equal to or lesser than the “Max.” value is applied, the input voltage is guaranteed as low level voltage.
Input rise time	T_{ri}	Indicates the limit value for the time period when an input voltage applied to the input pins of the device rises from 10% to 90%.
Input fall time	T_{fi}	Indicates the limit value for the time period when an input voltage applied to the input pins of the device falls from 90% to 10%.
Operating temperature	T_A	Indicates the ambient temperature range for normal logic operations.

Table 3-3. Term Used in DC Characteristics

Parameter	Symbol	Meaning
Off-state output leakage current	I_{OZ}	Indicates the current that flows from the power supply pins when the rated power supply voltage is applied whena 3-state output has high impedance.
Input leakage current	I_I	Indicates the current that flows when the input voltage is supplied to the input pin.

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3.3 Absolute Maximum Ratings

Table 3-4. Absolute Maximum Ratings

Parameter	Symbol	Condition	Rating	Units
Power supply voltage	V_{DD33}, AV_{DD33}		−0.5 to +4.6	V
	V_{DD10}		−0.5 to +1.4	V
	$AV_{DD33IN1}$, $AV_{DD33IN2}$		−0.5 to +4.6	V
Input voltage, 3.3 V buffer	V_I	$V_I < V_{DD33}$ + 0.5 V	−0.5 to +4.6	V
Output voltage, 3.3 V buffer	V_O	$V_O < V_{DD33}$ + 0.5 V	−0.5 to +4.6	V
USB3.0 differential signals	V_I/V_O	$V_I/V_O < V_{DD10}$ + 0.5 V	−0.5 to +1.4	V
Input voltage, 5 V tolerant buffer	V_I	$V_I < V_{DD33}$ + 2.5 V	−0.5 to +6.6	V
Output current	I_O	4 mA Type	8	mA
	I_O	12 mA Type	24	mA
Storage temperature	T_{stg}		−65 to +125	°C

Caution Product quality may suffer if the absolute maximum rating is exceeded even momentarily for any parameters. That is, the absolute maximum ratings are rated values at which the product is on the verge of suffering physical damage, and therefore the product must be used under conditions that ensure that the absolute maximum ratings are not exceeded. The ratings and conditions indicated for DC characteristics and AC characteristics represent the quality assurance range during normal operation.

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3.4 Recommended Operating Ranges

Table 3-5. Recommended Operating Ranges

Parameter	Symbol	Condition	Min.	Typ.	Max.	Units
Operating voltage With external power source	V_{DD33}, AV_{DD33}		3.0	3.3	3.6	V
	V_{DD10}		0.9975	1.05	1.1025	V
Operating voltage With on-chip Regulators	$AV_{DD33IN1}$, $AV_{DD33IN2}$		3.0	3.3	3.6	V
High-level input voltage	V_{IH}		2.0		V_{DD33}+0.3	V
Low-level input voltage	V_{IL}		–0.3		0.8	V
Input rise time	T_{ri}	Normal Buffer Schmitt Buffer	0 0		200 10	ns ms
Input fall time	T_{fi}	Normal Buffer Schmitt Buffer	0 0		200 10	ns ms
Operating ambient temperature (μPD720211K8-611-BAL-A, μPD720211K8-611-BAL-M1-A)	T_A		0		+70	°C
Operating ambient temperature (μPD720211K8-711-BAL-A, μPD720211K8-711-BAL-M1-A)	T_A		–40		+70	°C

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3.5 DC Characteristics

Table 3-6. DC Characteristics (V_{DD33} = 3.3 V ± 10%, V_{DD10} = 1.05 V ± 5%)

Parameter	Symbol	Condition	Min.	Max.	Units
Off-state output current	I_{OZ}	$V_I = V_{DD33}$ or GND		±10	μA
Input leakage current	I_I	$V_I = V_{DD33}$ or GND		±10	μA
Low-level output voltage	V_{OL}	I_{OL} = 0 mA		0.1	V
High-level output voltage	V_{OH}	I_{OH} = 0 mA	V_{DD33}–0.1		V

Table 3-7. USB Interface Block

Parameter	Symbol	Conditions	Min.	Max.	Unit
Output pin impedance	Z_{HSDRV}		40.5	49.5	Ω
Input Levels for Low-/Full-speed:					
High-level input voltage (drive)	V_{IH}		2.0		V
High-level input voltage (floating)	V_{IHZ}		2.7	3.6	V
Low-level input voltage	V_{IL}			0.8	V
Differential input sensitivity	V_{DI}	|(D+) – (D–)|	0.2		V
Differential common mode range	V_{CM}	Includes V_{DI} range	0.8	2.5	V
Output Levels for Low-/Full-speed:					
High-level output voltage	V_{OH}	RL of 14.25 kΩ to GND	2.8	3.6	V
Low-level output voltage	V_{OL}	RL of 1.425 kΩ to 3.6 V	0.0	0.3	V
SE1	V_{OSE1}		0.8		V
Output signal crossover point voltage	V_{CRS}		1.3	2.0	V
Input Levels for High-speed:					
High-speed squelch detection threshold (differential signal)	V_{HSSQ}		100	150	mV
High-speed disconnect detection threshold (differential signal)	V_{HSDSC}		525	625	mV
High-speed data signaling common mode voltage range	V_{HSCM}		–50	+500	mV
High-speed differential input signaling level	See Figure 3-4				
Output Levels for High-speed:					
High-speed idle state	V_{HSOI}		–10	+10	mV
High-speed data signaling high	V_{HSOH}		360	440	mV
High-speed data signaling low	V_{HSOL}		–10	+10	mV
Chirp J level (differential signal)	V_{CHIRPJ}		700	1100	mV
Chirp K level (differential signal)	V_{CHIRPK}		–900	–500	mV

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Figure 3-1. Differential Input Sensitivity Range for Low-/Full-speed

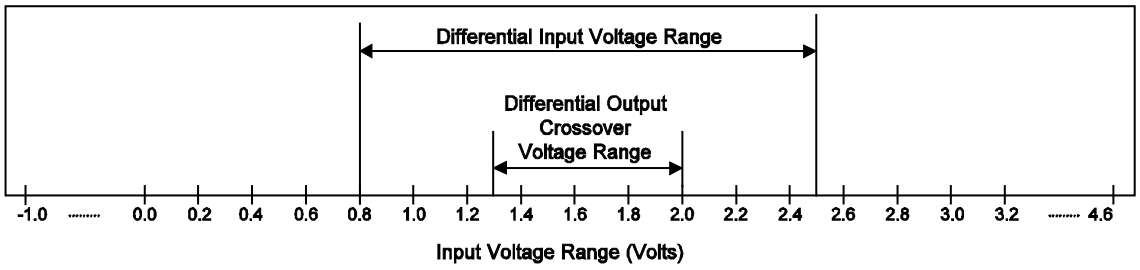


Figure 3-2. Full-speed Buffer V_{OH}/I_{OH} Characteristics for High-speed Capable Transceiver

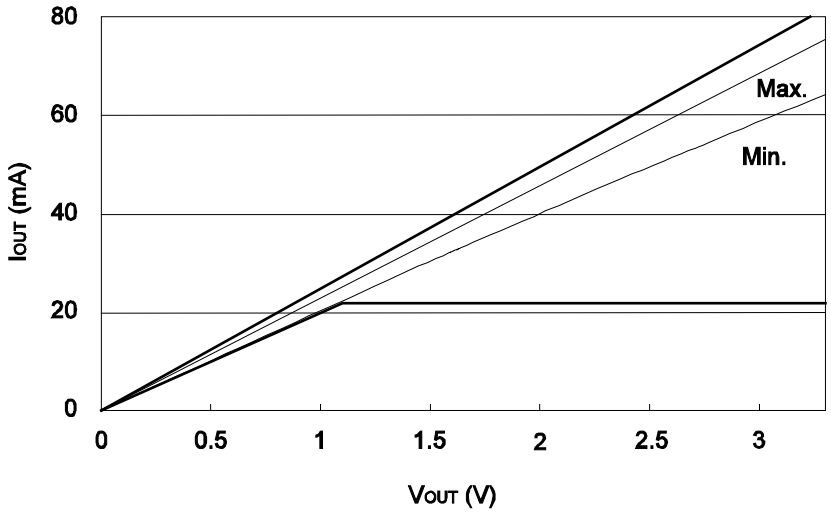
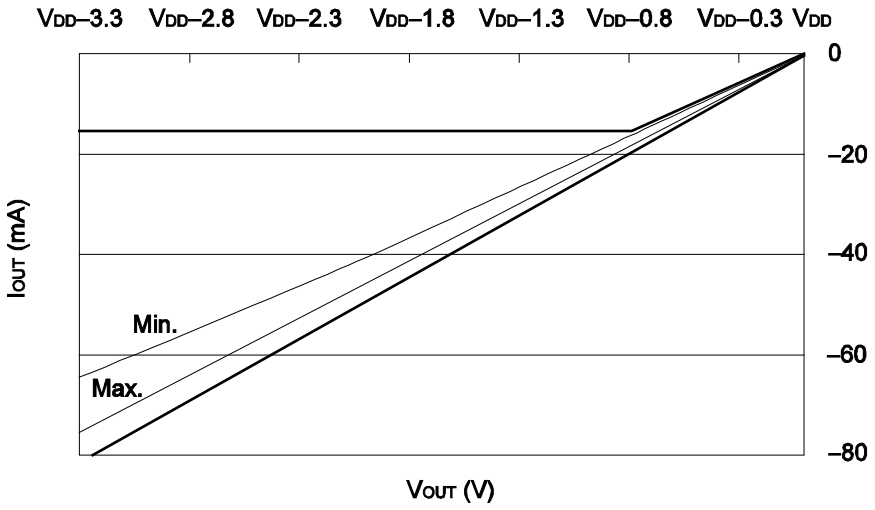


Figure 3-3. Full-speed Buffer V_{OL}/I_{OL} Characteristics for High-speed Capable Transceiver



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Figure 3-4. Receiver Sensitivity for Transceiver at DP/DM

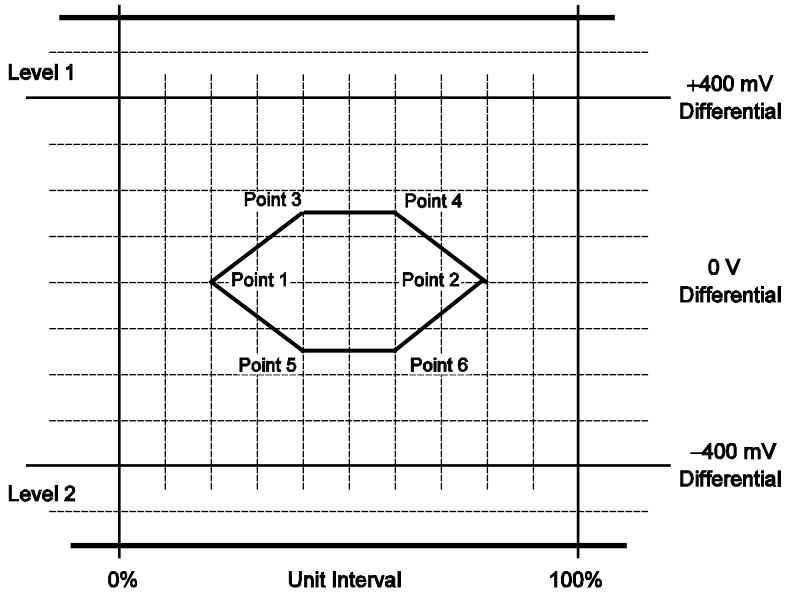


Figure 3-5. Receiver Measurement Fixtures

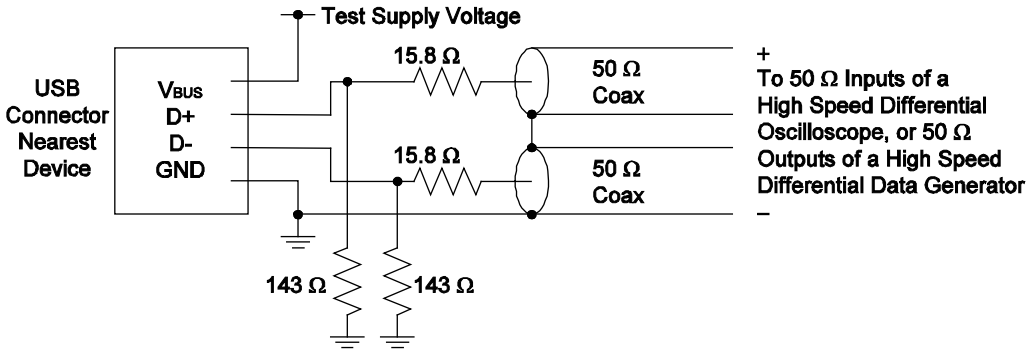


Table 3-8. Cut Off Current of On-chip Regulators

Parameter	Symbol	Condition	Min.	Max.	Units
Cut-off current of on-chip regulator (1.05 V)	$I_{cutoff1}$	-	1.5		A

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3.6 Pin Capacitance

Table 3-9. Pin Capacitance

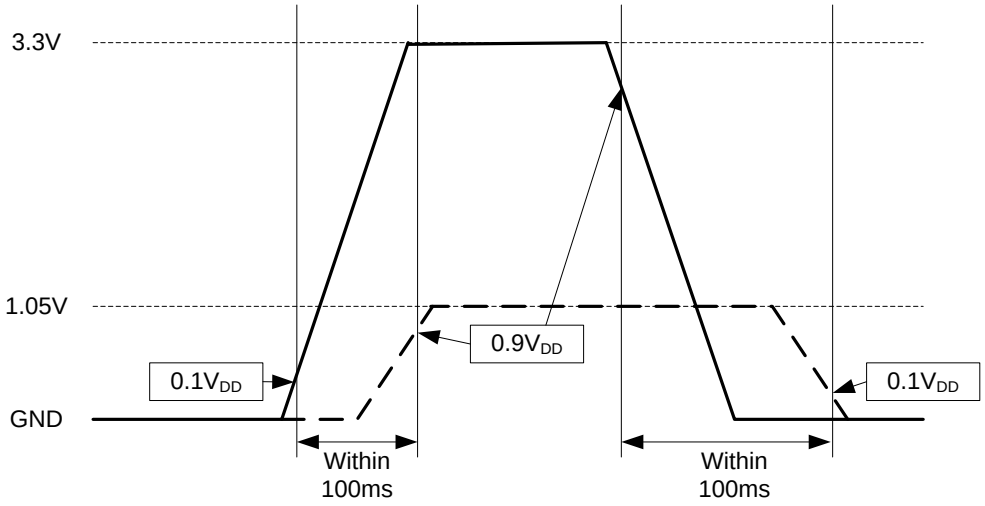
Parameter	Symbol	Condition	Min.	Max.	Units
System Interface Pins capacitance	C_{sys}			5	pF
USB Port Control Pins capacitance	C_{Por}			5	pF
SPI interface pin capacitance	C_{SPI}			5	pF

3.7 Sequence for Turning On or Off Power

When the external power source for 1.05 V and 3.3 V power is used, it is recommended that the time difference between the start of power-supply rise (3.3 V or 1.05 V) and the point where both power supplies are stabilized should be within 100 ms, regardless of the order of power sequence. A voltage of $0.1V_{DD}$ has to be raised to $0.9V_{DD}$ within the specified time.

When the on-chip LDO and the switching regulator are used, this timing is controlled by the internal circuit as defined here.

Figure 3-6. Order of Power Sequence



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3.8 AC Characteristics

3.8.1 System Clock

Table 3-10. System Clock (XT1/XT2) Ratings (V_{DD33} = 3.3 V ± 10%, V_{DD10} = 1.05 V ± 5%)

Parameter	Symbol	Condition	Min.	Typ.	Max.	Units
Clock frequency	F_{CLK}	Crystal	−100 ppm	24	+100 ppm	MHz
Clock duty cycle	T_{DUTY}		40	50	60	%

Remark Required accuracy of crystal or oscillator block includes initial frequency accuracy, the spread of Crystal capacitor loading, supply voltage, temperature and aging, etc.

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3.8.2 Reset and Clock Timing

Table 3-11. Power on Reset (RESETB) Timings

Parameter	Symbol	Condition	Min.	Max.	Units
Power on reset time	T_{PONRST}	See Figure 3-7	10		ms

Remarks 1. There is no required order for powering-on V_{DD33}, AV_{DD33}, and V_{DD10}.

2. All power sources should be stable within 100 ms from the earliest turned on power source.

3. RESETB shall be de-asserted after all power sources and the system clock become stable.

Figure 3-7. Power on Reset Timing

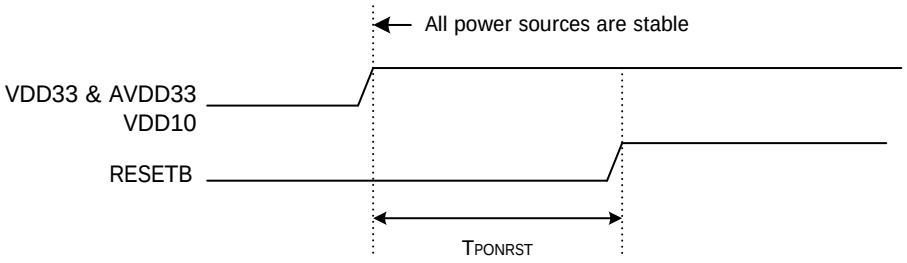
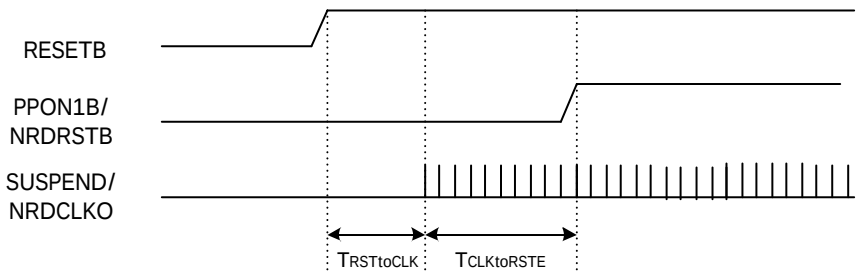


Table 3-12. NRDRST Output and CLKOUT Signal Timing

Parameter	Symbol	Condition	Min.	Max.	Units
Clock out timing after Reset out ends	$T_{RSTtoCLK}$	See Figure 3-8		300	μs
Reset timing for Non-Removable Device after Clock out starts	$T_{CLKtoRSTE}$	See Figure 3-8		30	ms

Figure 3-8. NRDRST Output and CLKOUT Signal Timing



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Table 3-13, Figure 3-9 shows the stopping timing of clock output of SUSPNED/NRDCLKO pin. There are three cases for the timing. To stop the clock output, a setting of ROM Writing Tool is needed. Refer to μPD720211 User's Manual (R19UH0100E) in more detail.

Case 1: Non-removable device of Port 1 is a USB 2.0 device.
After a USB 2.0 non-removable device of Port1 transitions to suspend state and the wait time of "$T_{U2CLKOFF}$" is satisfied, the clock output stops.

Case 2: Non-removable device of Port 1 is a USB 3.0 device except USB 3.0 hub.
After a USB 3.0 non-removable device of Port1 transitions to suspend state and the wait time of "$T_{U3CLKOFF}$" is satisfied, the clock output stops.

Case 3: Non-removable device of Port 1 is a USB 3.0 hub.
After a USB 3.0 non-removable hub of Port1 transitions to suspend state and the wait time of "$T_{U2CLKOFF}$" and "$T_{U3CLKOFF}$" is satisfied, the clock output stops.

Table 3-13. NRDCLKO Clock Output Stop Timing

Parameter	Symbol	Condition	Min.	Max.	Units
Wait time of stopping Clock Output after Non-Removable USB 2.0 Device transitions to Suspend state (Note1)	$T_{U2CLKOFF}$	See Figure 3-9		50	ms
Wait time of stopping Clock Output after Non-Removable USB 3.0 Device transitions to Suspend state (Note2)	$T_{U3CLKOFF}$	See Figure 3-9		50	ms

Notes 1. If USB 2.0 Port 1 detects any resume signal during this wait time, μPD720211 doesn't stop the clock output for non-removable device.

2. If USB 3.0 Port 1 detects U3exit during this wait time, μPD720211 doesn't stop the clock output for non-removable device.

Figure 3-9. NRDCLKO Clock Output Stop Timing

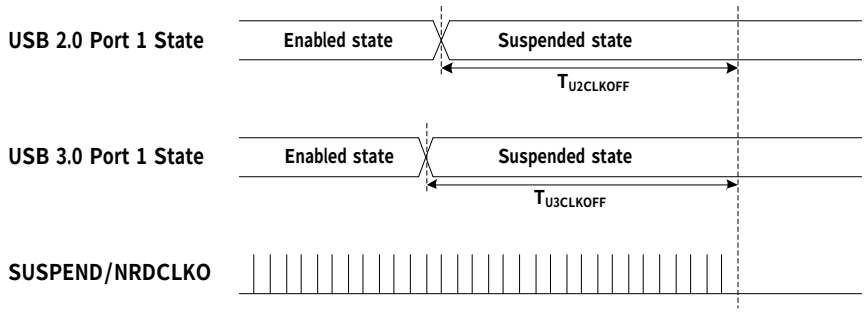


Table 3-14, Figure 3-10, Figure 3-11 and Figure 3-12 shows the starting timing of clock output of SUSPNED/NRDCLKO pin after stopping the clock output. There are three cases for the timing.

Case 1: Non-removable device of Port 1 is a USB 2.0 device.
If "$T_{CLKONbyU2R}$" or "$T_{CLKONbyU2T}$" or "$T_{CLKONbyU2Sta}$" is satisfied, the clock output is initiated.

Case 2: Non-removable device of Port 1 is a USB 3.0 device except USB 3.0 hub.
If "$T_{CLKONbyU3R}$" or "$T_{CLKONbyU3T}$" is satisfied, the clock output is initiated.

Case 3: Non-removable device of Port 1 is a USB 3.0 hub.
If "$T_{CLKONbyU2R}$" or "$T_{CLKONbyU2T}$" or "$T_{CLKONbyU2Sta}$" or "$T_{CLKONbyU3R}$" or "$T_{CLKONbyU3T}$" is satisfied, the clock output is initiated.

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Table 3-14. NRDCLKO Clock Output Start Timing

Parameter	Symbol	Condition	Min.	Max.	Units
Start timing of Clock Output after sending resume signal or detecting resume signal on USB 2.0 Port 1	$T_{CLKONbyU2R}$	See Figure 3-10		1	ms
Start timing of Clock Output after transitioning to not suspended state on USB 2.0 Port 1	$T_{CLKONbyU2T}$	See Figure 3-10		1	ms
Start timing of Clock Output after transitioning to not suspended state on USB 2.0 Upstream	$T_{CLKONbyU2Sta}$	See Figure 3-11		1	ms
Start timing of Clock Output after sending U3exit or detecting U3exit on USB 3.0 Port 1	$T_{CLKONbyU3R}$	See Figure 3-12		1	ms
Start timing of Clock Output after transitioning to not suspended state on USB 3.0 Port 1	$T_{CLKONbyU3T}$	See Figure 3-12		1	ms

Figure 3-10. NRDCLKO Clock Output Start Timing by Resuming USB 2.0 Port 1

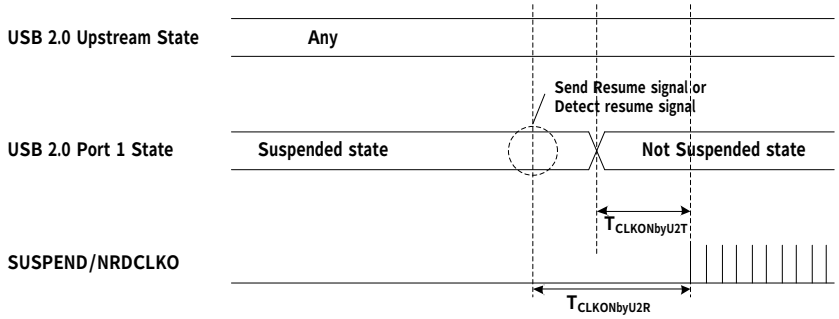
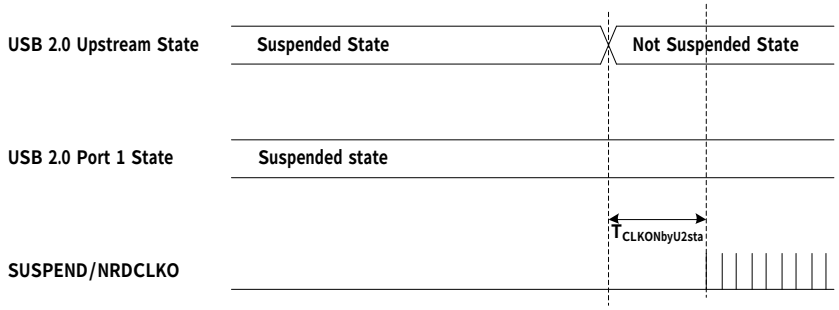
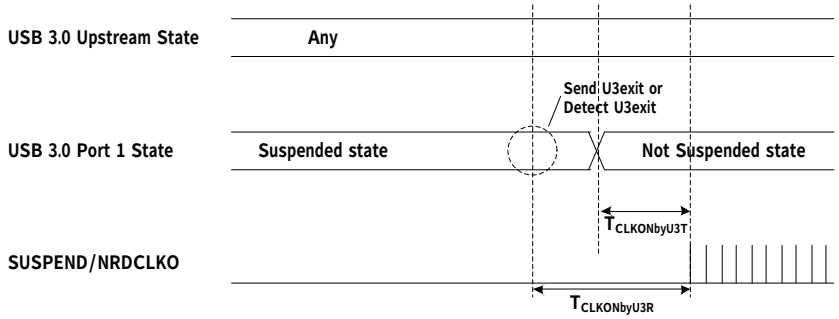


Figure 3-11. NRDCLKO Clock Output Initiate Timing by USB 2.0 Upstream State Transition



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Figure 3-12. NRDCLKO Clock Output Initiate Timing by Resuming USB 3.0 Port 1



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3.8.3 USB3.0 SuperSpeed Interface – Differential Transmitter (TX) Specifications

(Refer to Universal Serial Bus 3.0 Specification Revision 1.0 for more information)

Table 3-15. Transmitter Normative Electrical Parameters

Parameter	Symbol	Min.	Max.	Units
Unit Interval	UI	199.94	200.06	ps
Differential p-p Tx voltage swing	$V_{TX-DIFF-PP}$	0.8	1.2	V
Tx de-emphasis	$V_{TX-DE-RATIO}$	3.0	4.0	dB
DC differential impedance	$R_{TX-DIFF-DC}$	72	120	Ω
The amount of voltage change allowed during Receiver Detection	$V_{TX-RCV-DETECT}$		0.6	V
AC Coupling Capacitor	$C_{AC-COUPLING}$	75	200	nF
Maximum slew rate	$t_{CDR-SLEW-MAX}$		10	ms/s

Table 3-16. Transmitter Informative Electrical Parameters

Parameter	Symbol	Min.	Max.	Units
Deterministic min pulse	$t_{MIN-PULSE-Dj}$	0.96		UI
Tx min pulse	$t_{MIN-PULSE-Tj}$	0.90		UI
Transmitter Eye	t_{TX-EYE}	0.625		UI
Tx deterministic jitter	$t_{TX-DJ-DD}$		0.205	UI
Tx input capacitance for return loss	$C_{TX-PARASITIC}$		1.25	pf
Transmitter DC common mode impedance	R_{TX-DC}	18	30	Ω
Transmitter short-circuit current limit	$I_{TX-SHORT}$		60	mA
Transmitter DC common-mode voltage	$V_{TX-DC-CM}$	0	2.2	V
Tx AC common mode voltage	$V_{TX-CM-AC-PP-ACTIVE}$		100	mVp-p
Absolute DC Common Mode Voltage between U1 and U0	$V_{TX-CM-DC-ACTIVE-IDLE-DELTA}$		200	mV
Electrical Idle Differential Peak- Peak Output voltage	$V_{TX-IDLE-DIFF-AC-pp}$	0	10	mV
DC Electrical Idle Differential Output Voltage	$V_{TX-IDLE-DIFF-DC}$	0	10	mV

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3.8.4 USB3.0 SuperSpeed Interface – Differential Receiver (RX) Specifications

(Refer to Universal Serial Bus 3.0 Specification Revision 1.0 for more information)

Table 3-17. Receiver Normative Electrical Parameters

Parameter	Symbol	Min.	Max.	Units
Unit Interval	UI	199.94	200.06	ps
Receiver DC common mode impedance	R_{RX-DC}	18	30	Ω
DC differential impedance	$R_{RX-DIFF-DC}$	72	120	Ω
DC Input CM Input Impedance for V>0 during Reset of Power down	$Z_{RX-HIGH-IMP-DC-POS}$	25k		Ω
LFPS Detect Threshold	$V_{RX-LFPS-DET-DIFF-p-p}$	100	300	mV

Table 3-18. Receiver Informative Electrical Parameters

Parameter	Symbol	Min.	Max.	Units
Differential Rx peak-to-peak voltage	$V_{RX-DIFF-PP-POST-EQ}$	30		mV
Max Rx inherent timing error	T_{RX-Tj}		0.45	UI
Max Rx inherent deterministic timing error	$T_{RX-DJ-DD}$		0.285	UI
Rx input capacitance for return loss	$C_{RX-PARASITIC}$		1.1	pF
Rx AC common mode voltage	$V_{RX-CM-AC-P}$		150	mVPeak
Rx AC common mode voltage during the U1 to U0 transition	$V_{RX-CM-DC-ACTIVE-IDLE-DELTA-P}$		200	mVPeak

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3.8.5 USB2.0 Interface

Table 3-19. USB Interface (1 of 4)

Parameter	Symbol	Conditions	Min.	Max.	Unit
Low-speed Electrical Characteristics					
Rise time (10% to 90%)	t_{LR}	C_L = 200 pF to 600 pF	75	300	ns
Fall time (90% to 10%)	t_{LF}	C_L = 200 pF to 600 pF	75	300	ns
Differential rise and fall time matching	t_{LRFM}	(t_{LR}/t_{LF}) **Note**	80	125	%
Low-speed data rate	$t_{LDRATHS}$	Average bit rate	1.49925	1.50075	Mbps
Downstream facing port source jitter total (including frequency tolerance) (**Figure 3-19**):					
To next transition	t_{DDJ1}		−25	+25	ns
For paired transitions	t_{DDJ2}		−14	+14	ns
Downstream facing port differential receiver jitter total (including frequency tolerance) (**Figure 3-19**):					
To next transition	t_{UJR1}		−152	+152	ns
For paired transitions	t_{UJR2}		−200	+200	ns
Source SE0 interval of EOP (**Figure 3-18**)	t_{LEOPT}		1.25	1.5	μs
Receiver SE0 interval of EOP (**Figure 3-18**)	t_{LEOPR}		670		ns
Width of SE0 interval during differential transition	t_{LST}			210	ns
Hub differential data delay (**Figure 3-15**)	t_{LHDD}			300	ns
Hub differential driver jitter (including cable) (**Figure 3-15**):					
Downstream facing port					
To next transition	t_{LDHJ1}		−45	+45	ns
For paired transitions	t_{LDHJ2}		−15	+15	ns
Upstream facing port					
To next transition	t_{LUHJ1}		−45	+45	ns
For paired transitions	t_{LUHJ2}		−45	+45	ns
Data bit width distortion after SOP (**Figure 3-15**)	t_{LSOP}		−60	+60	ns
Hub EOP delay relative to t_{HDD} (**Figure 3-16**)	t_{LEOPD}		0	200	ns
Hub EOP output width skew (**Figure 3-16**)	t_{LHESK}		−300	+300	ns
Full-speed Electrical Characteristics					
Rise time (10% to 90%)	t_{FR}	C_L = 50 pF, R_S = 36 Ω	4	20	ns
Fall time (90% to 10%)	t_{FF}	C_L = 50 pF, R_S = 36 Ω	4	20	ns
Differential rise and fall time matching	t_{FRFM}	(t_{FR}/t_{FF})	90	111.11	%
Full-speed data rate	$t_{FDRATHS}$	Average bit rate	11.9940	12.0060	Mbps
Frame interval	t_{FRAME}		0.9995	1.0005	ms

Note Excluding the first transition from the Idle state.

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Table 3-20. USB Interface (2 of 4)

Parameter	Symbol	Conditions	Min.	Max.	Unit
Full-speed Electrical Characteristics (Continued)					
Consecutive frame interval jitter	t_{RFI}	No clock adjustment		42	ns
Source jitter total (including frequency tolerance) (**Figure 3-17**):		**Note**			
To next transition	t_{DJ1}		–3.5	+3.5	ns
For paired transitions	t_{DJ2}		–4.0	+4.0	ns
Source jitter for differential transition to SE0 transition (**Figure 3-18**)	t_{FDEOP}		–2	+5	ns
Receiver jitter (**Figure 3-19**):					
To Next Transition	t_{JR1}		–18.5	+18.5	ns
For Paired Transitions	t_{JR2}		–9	+9	ns
Source SE0 interval of EOP (**Figure 3-18**)	t_{FEOPT}		160	175	ns
Receiver SE0 interval of EOP (**Figure 3-18**)	t_{FEOPR}		82		ns
Width of SE0 interval during differential transition	t_{FST}			14	ns
Hub differential data delay (**Figure 3-15**)					
(with cable)	t_{HDD1}			70	ns
(without cable)	t_{HDD2}			44	ns
Hub differential driver jitter (including cable) (**Figure 3-15**):					
To next transition	t_{HDJ1}		–3	+3	ns
For paired transitions	t_{HDJ2}		–1	+1	ns
Data bit width distortion after SOP (**Figure 3-15**)	t_{FSOP}		–5	+5	ns
Hub EOP delay relative to t_{HDD} (**Figure 3-16**)	t_{FEOPD}		0	15	ns
Hub EOP output width skew (**Figure 3-16**)	t_{FHESK}		–15	+15	ns
High-speed Electrical Characteristics					
Rise time (10% to 90%)	t_{HSR}		500		ps
Fall time (90% to 10%)	t_{HSF}		500		ps
Driver waveform	See **Figure 3-13**.				
High-speed data rate	t_{HSDRAT}		479.760	480.240	Mbps
Microframe interval	t_{HSFRAM}		124.9375	125.0625	μs
Consecutive microframe interval difference	t_{HSRFI}			4 High-speed	Bit times
Data source jitter	See **Figure 3-13**.				
Receiver jitter tolerance	See **Figure 3-4**.				
Hub data delay (without cable)	t_{HSHDD}			36 High-speed+4 ns	Bit times
Hub data jitter	See **Figure 3-4**, **Figure 3-13**.				
Hub delay variation range	t_{HSHDV}			5 High-speed	Bit times

Note Excluding the first transition from the Idle state.

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Table 3-21. USB Interface (3 of 4)

Parameter	Symbol	Conditions	Min.	Max.	Unit
Hub Event Timings					
Time to detect a downstream facing port connect event (**Figure 3-21**): Awake hub Suspended hub	t_{DCNN}		 2.5 2.5	 2000 12000	 μs μs
Time to detect a disconnect event at a hub's downstream facing port (**Figure 3-20**)	t_{DDIS}		2.0	2.5	μs
Duration of driving resume to a downstream port (only from a controlling hub)	t_{DRSMDN}		20		ms
Time from detecting downstream resume to rebroadcast	t_{URSM}			1.0	ms
Duration of driving reset to a downstream facing port	t_{DRST}	Only for a SetPortFeature (PORT_RESET) request	10	20	ms
Time to detect a long K from upstream	t_{URLK}		2.5	100	μs
Time to detect a long SE0 from upstream	t_{URLSE0}		2.5	10000	μs
Duration of repeating SE0 upstream (for Low-/Full-speed repeater)	t_{URPSE0}			23	FS Bit times
Inter-packet delay (for High-speed) of packets traveling in same direction	$t_{HSIPDSD}$		88		Bit times
Inter-packet delay (for High-speed) of packets traveling in opposite direction	$t_{HSIPDOD}$		8		Bit times
Inter-packet delay for device/root hub response with detachable cable for High-speed	$t_{HSRSPIPD1}$			192	Bit times
Time of which a Chirp J or Chirp K must be continuously detected (filtered) by hub or device during Reset handshake	t_{FILT}		2.5		μs
Time after end of device Chirp K by which hub must start driving first Chirp K in the hub's chirp sequence	t_{WTDCH}			100	μs
Time for which each individual Chirp J or Chirp K in the chirp sequence is driven downstream by hub during reset	t_{DCHBIT}		40	60	μs
Time before end of reset by which a hub must end its downstream chirp sequence	t_{DCHSE0}		100	500	μs
Period of idle bus before device can initiate resume	t_{WTRSM}		5		ms
Duration of driving resume upstream	t_{DRSMUP}		1	15	ms

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Table 3-22. USB Interface (4 of 4)

Parameter	Symbol	Conditions	Min.	Max.	Unit
Hub Event Timings (Continued)					
Time to detect a reset from upstream for non High-speed capable devices	t_{DETRST}		2.5	10000	μs
Inter-packet delay for Full-speed	t_{IPD}		2		Bit times
Inter-packet delay for device response with detachable cable for Full-speed	$t_{RSPIPD1}$			6.5	Bit times
SetAddress() completion time	$t_{DSETADDR}$			50	ms
Time to complete standard request with no data	$t_{DRQCMPLTND}$			50	ms
Time to deliver first and subsequent (except last) data for standard request	$t_{DRETDATA1}$			500	ms
Time to deliver last data for standard request	$t_{DRETDATAN}$			50	ms
Time for which a suspended hub will see a continuous SE0 on upstream before beginning the High-speed detection handshake	$t_{FILTSE0}$		2.5		μs
Time a hub operating in non-suspended Full-speed will wait after start of SE0 on upstream before beginning the High-speed detection handshake	$t_{WTRSTFS}$		2.5	3000	ms
Time a hub operating in High-speed will wait after start of SE0 on upstream before reverting to Full-speed	t_{WTREV}		3.0	3.125	ms
Time a hub will wait after reverting to Full-speed before sampling the bus state on upstream and beginning the High-speed will wait after start of SE0 on upstream before reverting to Full-speed	$t_{WTRSTHS}$		100	875	ms
Minimum duration of a Chirp K on upstream from a hub within the reset protocol	t_{UCH}		1.0		ms
Time after start of SE0 on upstream by which a hub will complete its Chirp K within the reset protocol	t_{UCHEND}			7.0	ms
Time between detection of downstream chip and entering High-speed state	t_{WTHS}			500	μs
Time after end of upstream Chirp at which hub reverts to Full-speed default state if no downstream Chirp is detected	t_{WTFS}		1.0	2.5	ms

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Figure 3-13. Transmit Waveform for Transceiver at DP/DM

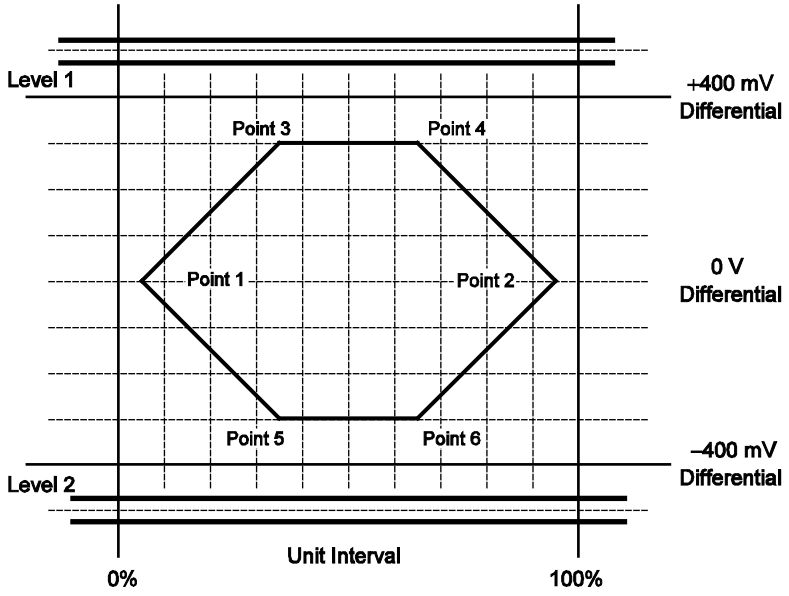
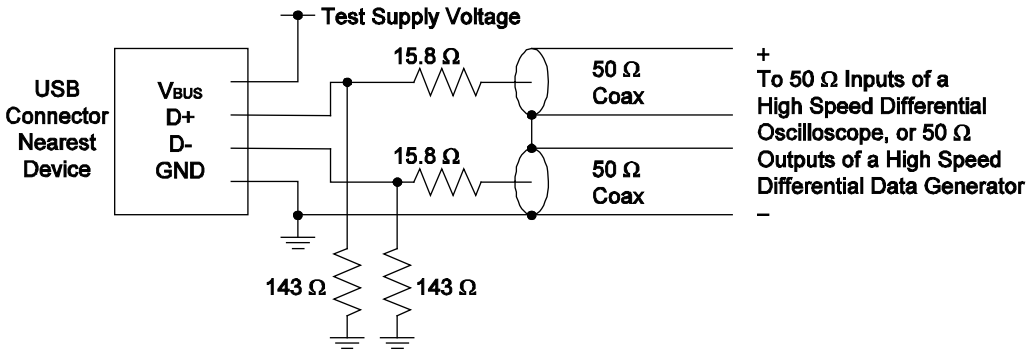
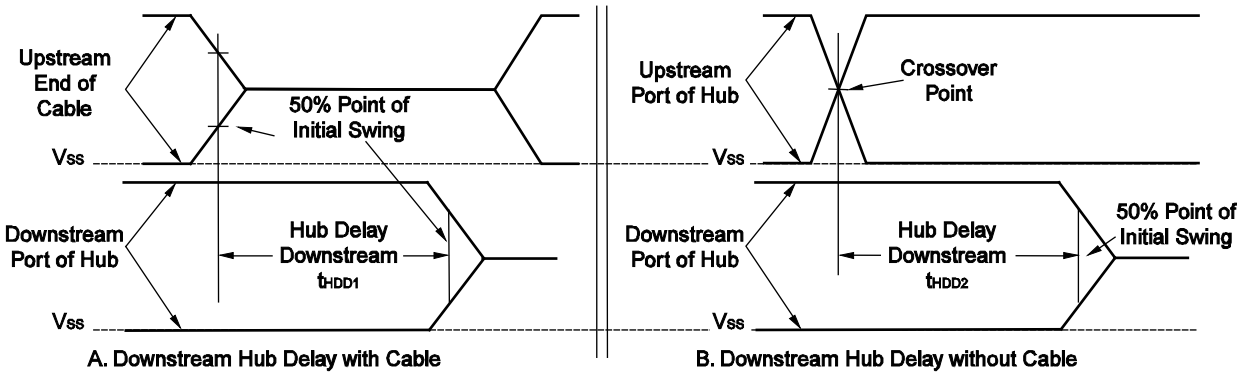


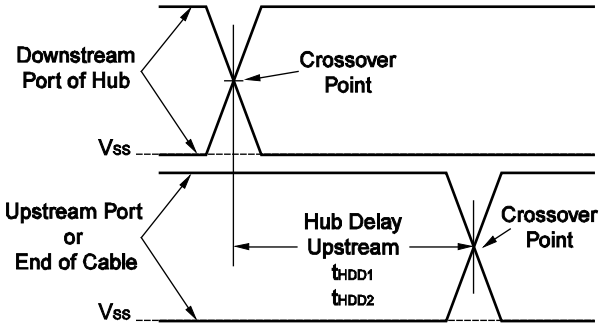
Figure 3-14. Transmitter Measurement Fixtures



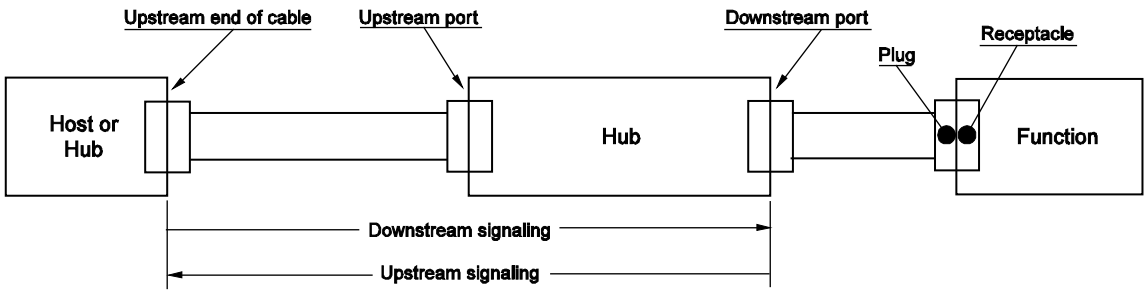
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Figure 3-15. Hub Differential Delay, Differential Jitter, and SOP Distortion





C. Upstream Hub Delay with or without Cable



D. Measurement Points

Hub Differential Jitter:

$t_{HDJ1} = t_{HDDx}(J) - t_{HDDx}(K)$ or $t_{HDDx}(K) - t_{HDDx}(J)$ Consecutive Transitions

$t_{HDJ2} = t_{HDDx}(J) - t_{HDDx}(J)$ or $t_{HDDx}(K) - t_{HDDx}(K)$ Paired Transitions

Bit after SOP Width Distortion (same as data jitter for SOP and next J transition):

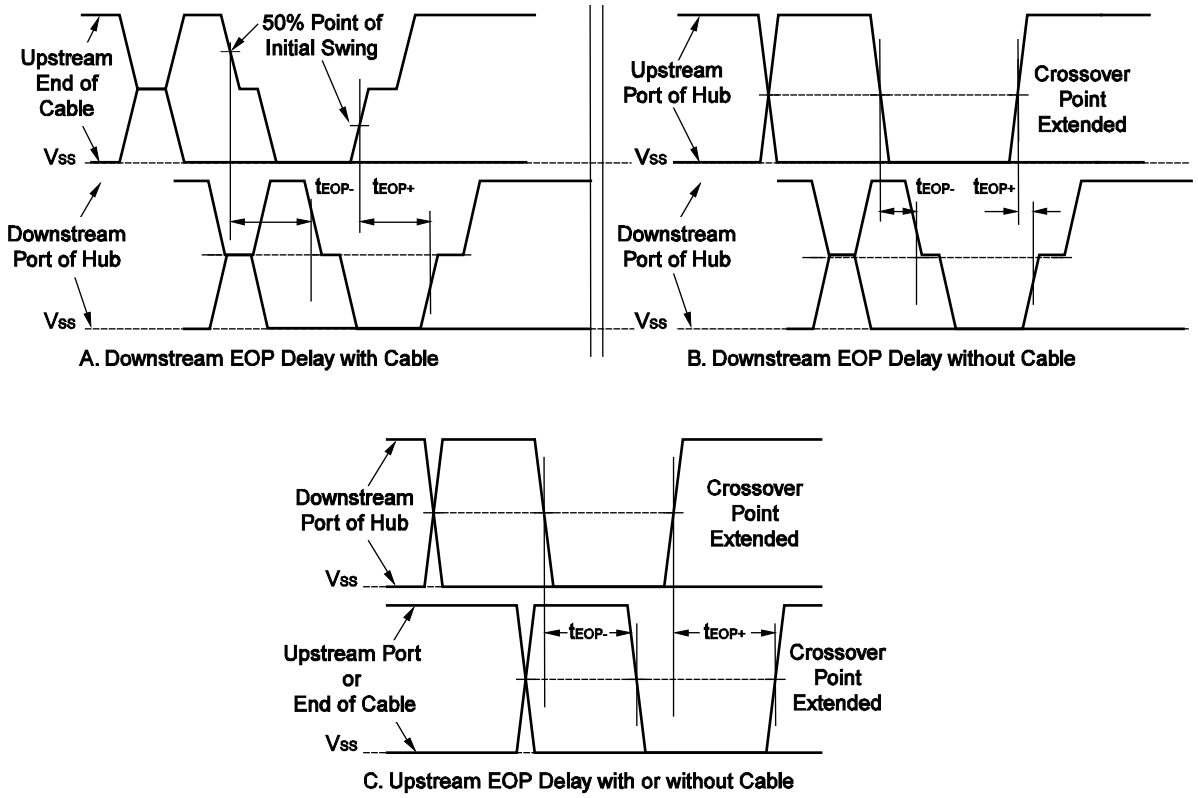
$t_{FSOP} = t_{HDDx}$(next J) – t_{HDDx}(SOP)

Low-speed timings are determined in the same way for:

t_{LHDD}, t_{LDHJ1}, t_{LDJH2}, t_{LUHJ1}, t_{LUJH2}, and t_{LSOP}

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Figure 3-16. Hub EOP Delay and EOP Skew



EOP Delay:

$t_{FEOPD} = t_{EOPy} - t_{HDDx}$

(t_{EOPy} means that this equation applies to t_{EOP-} and t_{EOP+})

EOP Skew:

$t_{FHESK} = t_{EOP+} - t_{EOP-}$

Low-speed timings are determined in the same way for:

t_{LEOPD} and t_{LHESK}

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Figure 3-17. USB Differential Data Jitter for Low-/Full-speed

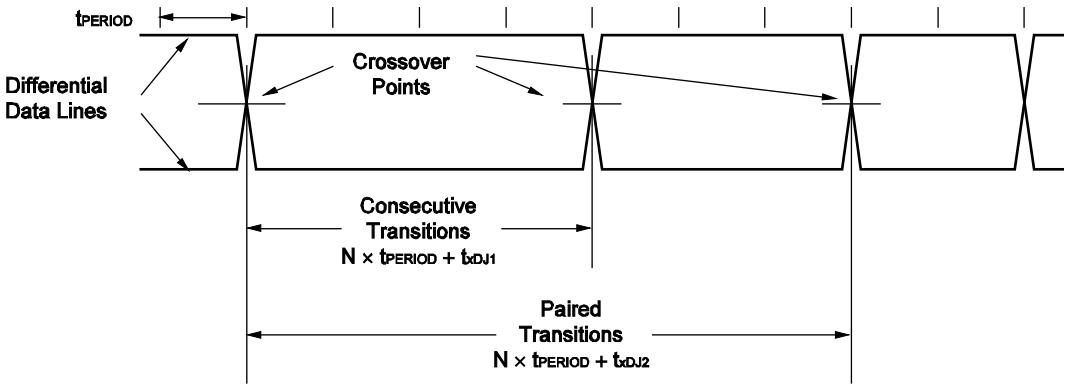


Figure 3-18. USB Differential-to-EOP Transition Skew and EOP Width for Low-/Full-speed

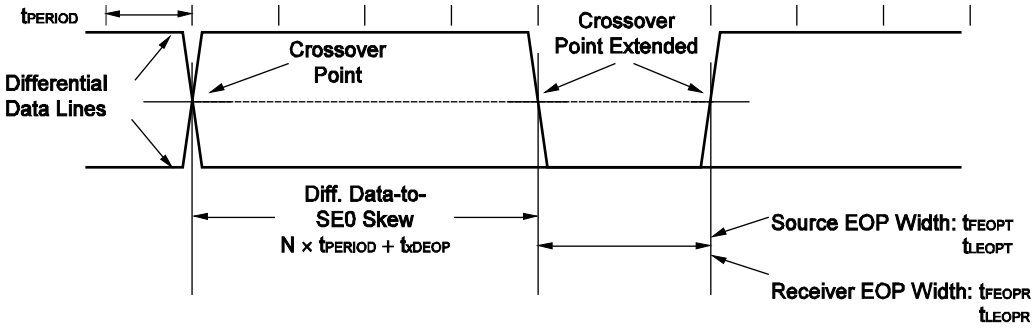
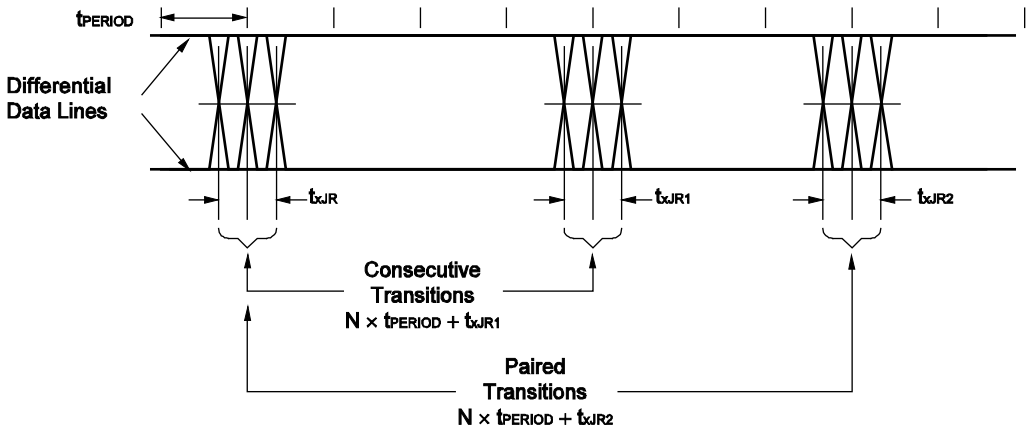


Figure 3-19. USB Receiver Jitter Tolerance for Low-/Full-speed



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Figure 3-20. Low-/Full-speed Disconnect Detection

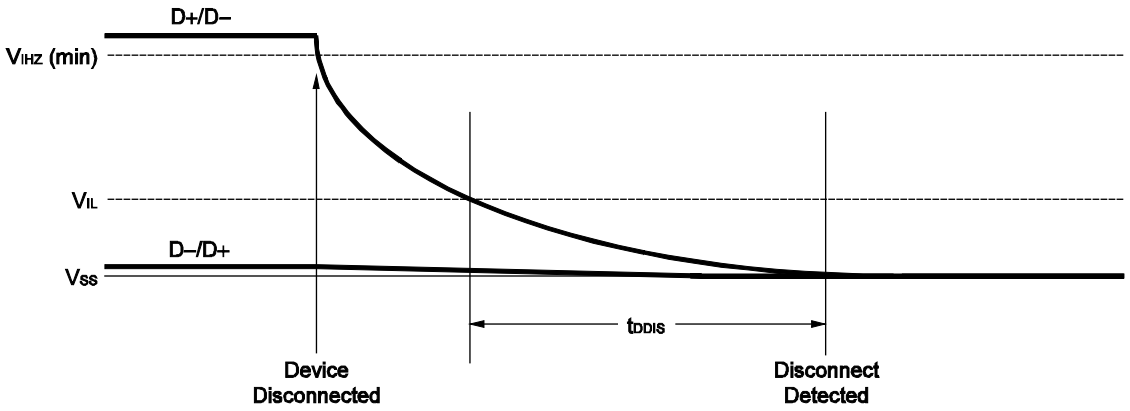
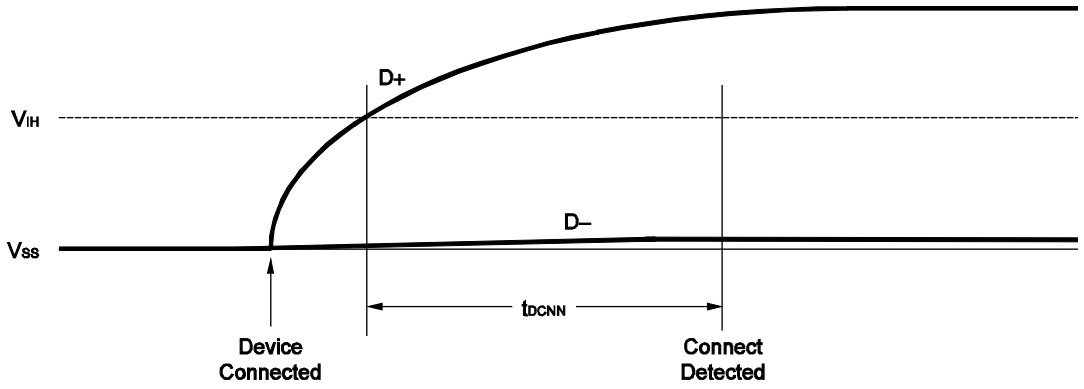


Figure 3-21. Full-/High-speed Device Connect Detection



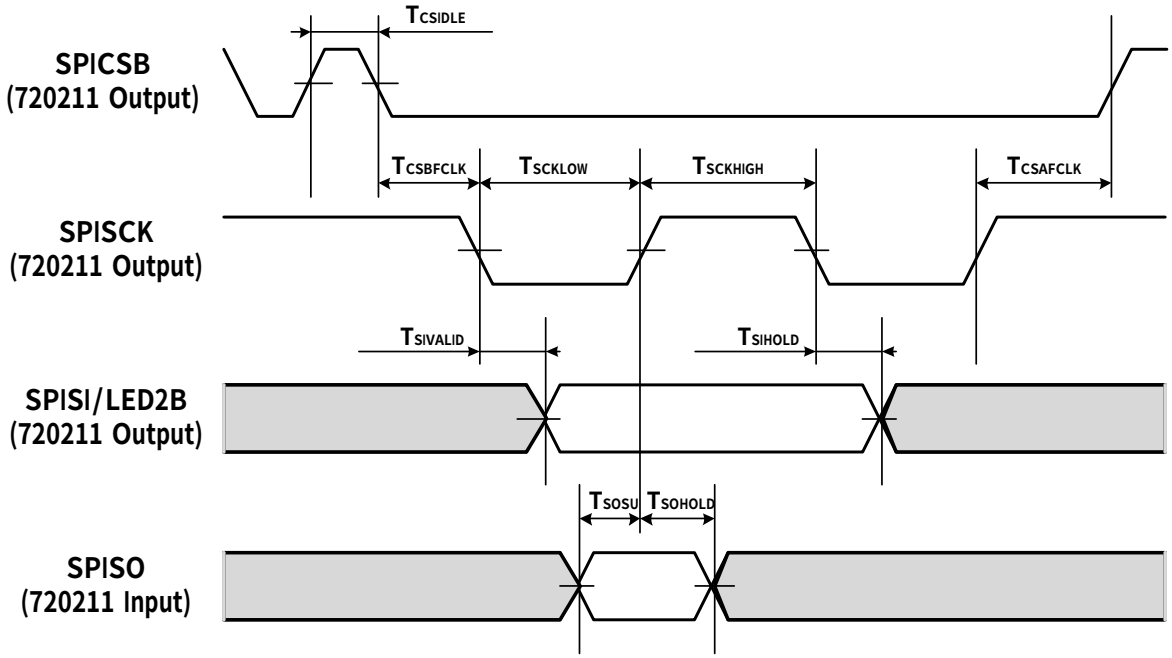
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3.8.6 SPI Type Serial ROM Interface

Table 3-23. SPI Type Serial ROM Interface Signals Timing (SPI Mode 0)

Parameter	Symbol	Min.	Max.	Units
SPISCK clock frequency		-	2.0	MHz
Chip select idle time	T_{CSIDEL}	500	-	ns
Chip select assertion time before clock	$T_{CSBFCLK}$	250	-	ns
Chip select deassertion time after clock	$T_{CSAFCLK}$	250	-	ns
Clock pulses width low	T_{SCKLOW}	250	-	ns
Clock pulses width high	$T_{SCKHIGH}$	250	-	ns
SPISI/LED2B validate time from SPISCK falling edge	$T_{SIVALID}$	-	10	ns
SPISI/LED2B hold time from SPISCK falling edge	T_{SIHOLD}	–10	10	ns
SPISO setup time to SPISCK rising edge	T_{SOSU}	5	-	ns
SPISO hold time from SPISCK rising edge	T_{SOHOLD}	5	-	ns

Figure 3-22. SPI Type Serial ROM Signal Timing



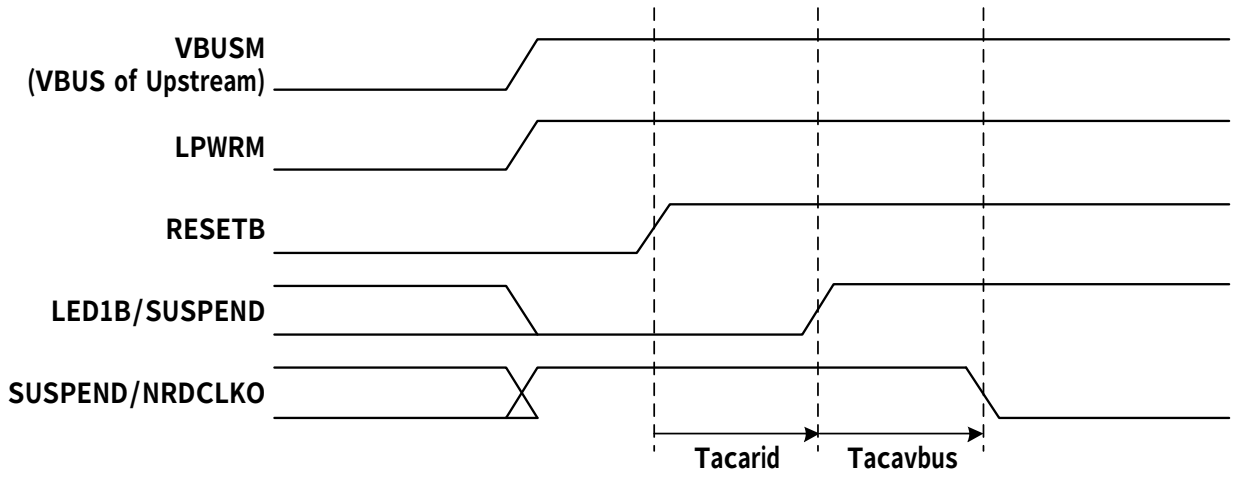
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3.8.7 ACA-Dock function control signal output timing

Table 3-24. ACA-Dock Function Control Signal Output Timing

Parameter	Symbol	Condition	Min.	Max.	Units
RID control signal of ACA-Dock function output timing	Tacarid	See Figure 3-24		100	ms
VBUS control signal of ACA-Dock function output timing	Tacavbus	See Figure 3-24		100	ms

Figure 3-23. SPI Type Serial ROM Signal Timing



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3.9 Power Consumption

Table 3-25. Power Consumption of μPD720211 (without On-chip Regulators Operating)

Parameter	Device connection	Condition	VDD10 line	VDD33 line	AVDD33 line	Units
Power Consumption	No host connection	Hub is not connected to host controller.	1.8	0.1	0.2	mA
	Global Suspend	Hub is connected to host controller both with SuperSpeed and HighSpeed. And the system is suspended (S3).				
		"Low Power Mode during suspend" function is enabled **Note2**	3.8	0.2	0.1	mA
		"Low Power Mode during suspend" function is disabled.	5.8	0.3	1.7	mA
	Selective Suspend	Hub is connected to host controller both with SuperSpeed and HighSpeed. The system is working and hub goes into U3 state.	5.8	0.3	1.7	mA
	1 device	Hub is connected to host controller both with SuperSpeed and HighSpeed. Only one device is connected on the port.				
		Low-speed data transfer on the port.	20	23	12	mA
		Full-speed data transfer on the port.	20	25	12	mA
		High-speed data transfer on the port.	22	53	12	mA
		SuperSpeed transfer on the port. **Note1**	278	1.5	12	mA
	2 devices	Hub is connected to host controller both with SuperSpeed and HighSpeed. Two devices are connected on the ports.				
		High-speed data transfer on the both ports.	25	76	12	mA
		SuperSpeed transfer on the both ports. **Note1**	386	1.5	12	mA
	2 SS hubs with SS and HS devices	Hub is connected to host controller both with SuperSpeed and HighSpeed . Two SuperSpeed hubs are connected on all ports under SS and HS data transfer.	437	75	23	mA

Typical condition (T_A = 25°C, V_{DD33} = 3.3 V, V_{DD10} = 1.05 V)

Notes 1. U1/U2 is enabled in this condition.

2. The external serial ROM is needed in order to set to enable Low power mode during suspend.

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Table 3-26. Power Consumption of μPD720211 (with On-chip Regulators)

Parameter	Device connection	Condition	Total Power **Note2**	Units
Power Consumption	No host connection	Hub is not connected to host controller.		
		"Low Power Mode during suspend" is enabled	6	mW
		"Low Power Mode during suspend" is disabled	13	mW
	Global Suspend	Hub is connected to host controller both with SuperSpeed and HighSpeed. And the system is suspended (S3).		
		"Low Power Mode during suspend" is enabled	10	mW
		"Low Power Mode during suspend" is disabled	23	mW
	Selective Suspend	Hub is connected to host controller both with SuperSpeed and HighSpeed. The system is working and hub goes into U3 state.		
		Low Power Mode during suspend is enabled	15	mW
		Low Power Mode during suspend is disabled	24	mW
	1 device	Hub is connected to host controller both with SuperSpeed and HighSpeed. Only one device is connected on the port.		
		Low-speed data transfer on the port.	140	mW
		Full-speed data transfer on the port.	150	mW
		High-speed data transfer on the port.	245	mW
		SuperSpeed transfer on the port. **Note1**	410	mW
	2 devices	Hub is connected to host controller both with SuperSpeed and HighSpeed. Two devices are connected on the ports.		
		High-speed data transfer on the both ports.	315	mW
		SuperSpeed transfer on the both ports. **Note1**	595	mW
	2 SS hubs with SS and HS devices	Hub is connected to host controller both with SuperSpeed and HighSpeed. Two SuperSpeed hubs are connected on all ports under SS and HS data transfer.	880	mW

Typical condition (T_A = 25°C, V_{DD33} = 3.3 V, V_{DD10} = 1.05 V)

Notes 1. U1/U2 is enabled in this condition.

2. The values on this page do NOT represent the chip's pure power consumption. The values include power loss by external components, too.

3. The external serial ROM is needed in order to set to enable Low power mode during suspend.

Remark Input voltage for on-chip regulators is 3.3 V.

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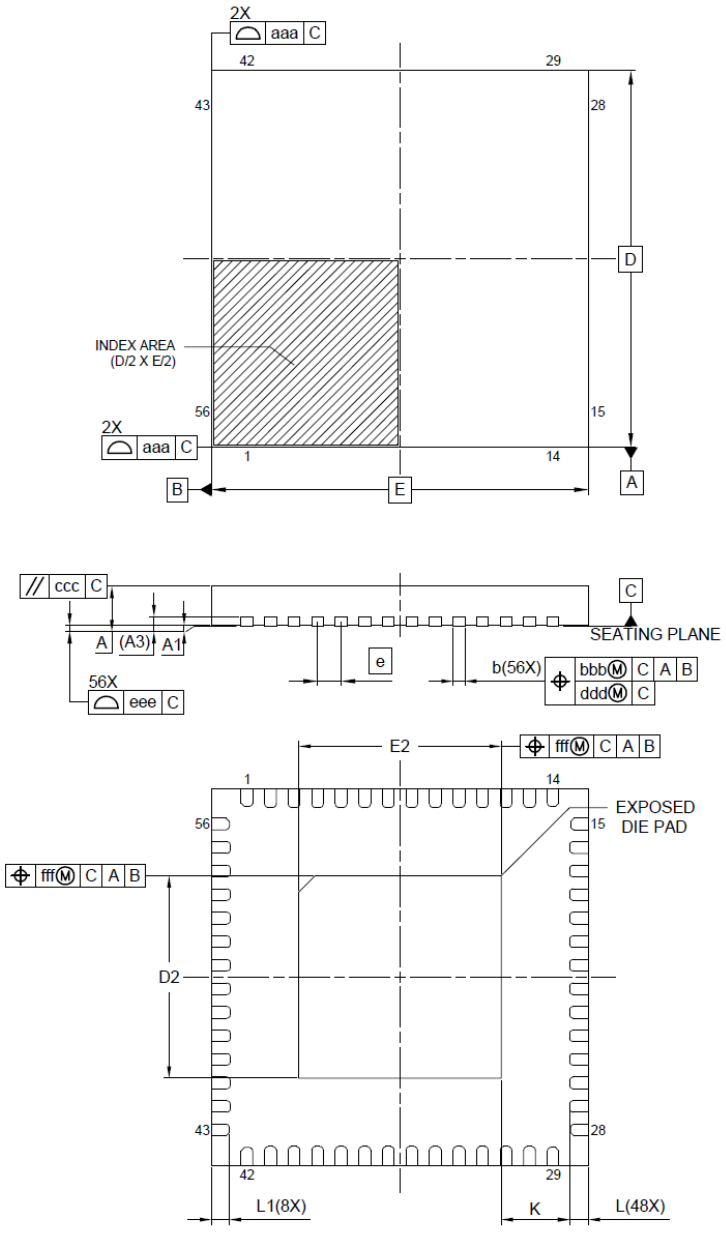
4. PACKAGE DRAWINGS

• μPD720211K8-611-BAL-A / μPD720211K8-611-BAL-M1-A

• μPD720211K8-711-BAL-A / μPD720211K8-711-BAL-M1-A

56- PIN QFN (8 × 8)

JEITA Package code	RENESAS code	MASS(TYP.)[g]
P-HVQFN056-8x8-0.50	PVQN0056KD-A	0.16



Reference Symbol	Dimension in Millimeters		
	Min.	Nom.	Max.
A	—	—	0.90
A1	0.00	0.02	0.05
A3		0.203 REF.	
b	0.20	0.25	0.30
D	—	8.00	—
E	—	8.00	—
e	—	0.50	—
L	0.35	0.40	0.45
L1	0.33	0.38	0.43
K	0.20	—	—
D2	4.25	4.30	4.35
E2	4.25	4.30	4.35
aaa	—	—	0.15
bbb	—	—	0.10
ccc	—	—	0.10
ddd	—	—	0.05
eee	—	—	0.08
fff	—	—	0.10

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5. RECOMMENDED SOLDERING CONDITIONS

The μPD720211 should be soldered and mounted under the following recommended conditions.
For soldering methods and conditions other than those recommended below, contact a Renesas Electronics sales representative.
For technical detail information, see the following website.

Semiconductor Package Mount Manual (http://www.renesas.com/products/package/index.jsp)

- μPD720211K8-611-BAL-A / μPD720211K8-611-BAL-M1-A
- μPD720211K8-711-BAL-A / μPD720211K8-711-BAL-M1-A

56-pin QFN (8 × 8)

Soldering Method	Soldering Conditions
Infrared reflow	Peak package's surface temperature: 260°C Reflow time: 30 seconds or less (Over 255°C) 60 to 150 seconds (217°C or higher) Maximum allowable number of reflow processes: 3 Exposure limit **Note**: 7 days (10 hours pre-backing is required at 125°C afterwards) <Caution> Non-heat-resistant trays, such as magazine and taping trays, cannot be baked before unpacking.

Note The Maximum number of days during which the product can be stored at a temperature of 5 to 30°C and a relative humidity of 70% or less after dry-pack package is opened.

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REVISION HISTORY	μPD720211 Data Sheet

Rev.	Date	Description	
		Page	Summary
0.01	July 17, 2013	-	First Edition issued
0.02	Sep. 30, 2013	-	Second Edition issued.
0.03	Oct. 22, 2013	-	● LED1B/SUSPEND, SPICSB, SPISO and SPISI/LED2B pin function description are modified in section 2.
0.04	Dec. 4, 2013	-	● Added the new part in section 1.3, 1.5, 4 and 5. ● Updated Table 1-1. ● Pin function descriptions are modified in section 2. ● Modified the buffer type of SUSPEND/NRDCLKO in section 3.1. ● Updated the cut-off current of on-chip regulator in Table 3-8.
0.05	Mar. 4, 2014	-	● Modified Table 3-12. NRDRST output and CLKOUT Signal Timing
		-	● Added Table 3-13, Table 3-14, Figure 3-9, Figure 3-10, Figure 3-11 and Figure 3-12.
		-	● Added section 3.8.7
		-	● Added section 3.8.8
		-	● Modified Table 3-26 Power Consumption of μPD720211 (without on-chip regulators operating)
		-	● Added Note 2 of Table 3-26
		-	● Modified Table 3-27 Power Consumption of μPD720211 (with on-chip regulators operating)
		-	● Added Note 3 of Table 3-27
		-	● Changed the package picture of 4. PACKAGE DRAWINGS.
1.00	Mar. 14, 2014	-	Document promoted from preliminary data to full data. (Document Number. R19DS0080E)
2.00	Jul. 24, 2014	-	● Delete the Note description in Table 3-5 Recommended Operating Ranges. ● Change section 4 PACKAGE DRAWING ● Change section 5 RECOMMENDED SOLDERING CONDITIONS
3.00	Nov. 25, 2014	- -	● Modified the feature to section 1.1 Features ● Modified the Function to section 2. Pin Function as below pins LX1 SUSPEND/NRDCLKO LED1B/SUSPEND SPICSB SPISI/LED2B
		-	● Modifiled section 3.1 Buffer List
		-	● Modified to Table 3-9
		-	● Modified typo of section 3.8.2
			● Added section 3.8.7 ACA-Dock function signal output timing
4.00	Sep 16, 2015	28,29	● Deleted the following parameters. t_{SIGATT}, t_{ATTDB}, $t_{SUSAVGI}$, t_{RSMRCY}, t_{RSTRCY}
		34	● Deleted Figure 3-22 “Power-on and Connection Events Timing”
		40	● Modified the URL

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Rev.	Date	Description	
		Page	Summary
5.00	Jun 30, 2023	-	● Added new part number
		-	● Removed unnecessary cross reference.
		40	● Replaced package drawing to latest version.
5.10	Sep 25, 2023	2	● Updated 1.3 Ordering Information

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(Rev.5.0-1 October 2020)

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